

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicants: Naoki KAWANABE, et al.  
Application No.: Not Yet Assigned  
Filed: On even date herewith  
For: A METHOD OF MANUFACTURING A SEMICONDUCTOR  
DEVICE TO PROVIDE IMPROVED ADHESION BETWEEN  
BONDING PADS AND BALL PORTIONS OF ELECTRICAL  
CONNECTORS (As Amended)  
Art Unit: Not Yet Assigned  
Examiner: Not Yet Assigned

**PRELIMINARY AMENDMENT**

Mail Stop Patent Application  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

March 24, 2004

Sir:

Prior to examination, please amend the above-identified application as listed below and as set forth on the following pages:

**Amendments to the Title;**

**Amendments to the Abstract;**

**Amendments to the Claims;**

**Remarks are included following the amendments; and**

**Appendix A including the new Abstract is attached following the remarks.**